

Appl. No. 10/811,124
Amdt. dated Nov. 7, 2005
Reply to Office action of Aug. 11, 2005

Remarks/Arguments

Applicants thank Examiner Andujar for his and careful examination of this application and clear explanation of the claim rejections. In response, applicants amend claims 1 and 16 to overcome the rejection; and cancel claims 17 and 18.

Claim 1

Claim 1 is amended to add the limitation of a second overcoat layer disposed on the integrated circuit and having an opening through which the bondable metal layer and a portion of the first overcoat layer are exposed. The exposed first overcoat is clearly depicted in Fig. 3B of this application, designated by reference numeral 370 and this element is not disclosed in the cited references.

First, APA does not show a second overcoat layer. Second, Huse does not disclose an opening in the second overcoat that exposes a portion of the first overcoat.

As explained in the Office action, Hsue, in fig. 4, shows an integrated circuit having a second overcoat layer at the edge of a window that is at or above a surface of a bondable layer. Figure 4, however, clearly depicts only the bondable layer 58 as being exposed through the opening in the second overcoat 60 while the first overcoat 54 is not exposed through the opening in the second overcoat.

Because the references do not disclose all the elements in claim 1, they do not anticipate, nor do they render claim 1 obvious. Therefore, applicants respectfully submit that claim 1 stands patentable.

Claim 16

Claim 16, as amended, include the additional element of depositing a second, organic, light-sensitive overcoat layer over said wafer and patterning the second overcoat to open a window through the thickness of the second overcoat layer to expose a portion of the first overcoat and the bondable metal layer.

As explained above relating to claim 1, Hsue does not disclose an opening in the second overcoat that exposes a portion of the first overcoat. This element

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is not disclosed in either the Sabin patent or in the Liu patent. Therefore, claim 16 is not anticipated by any one of the references cited against claim 16; and they do not render claim 16 obvious. Applicants respectfully submit that claim 16, as amended, stands patentable.

Claims 2-15

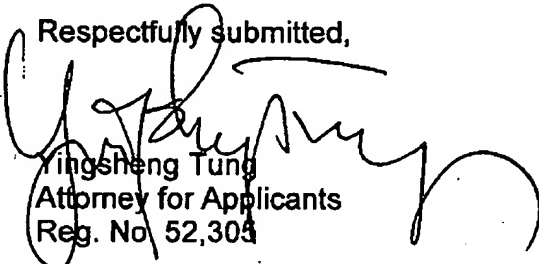
Claims 2-15 properly depend from claim 1. Because claim 1 as amended is not obvious, claim 2-15 also must not be obvious. Applicants respectfully submit that claims 2-15 stand patentable.

Claims 19 and 20

Claims 19 and 20 properly depend from claim 16. Because claim 16 is not obvious, claims 19 and 20 also must not be obvious. Applicants respectfully submit that claims 19 and 20 stand patentable.

In summary, applicants respectfully submit that this application is in allowable form and claims 1-16 and 19-20 distinguish over the cited references and stand patentable. Applicants respectfully request further examination of this application and timely allowance of all pending claims.

Respectfully submitted,


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